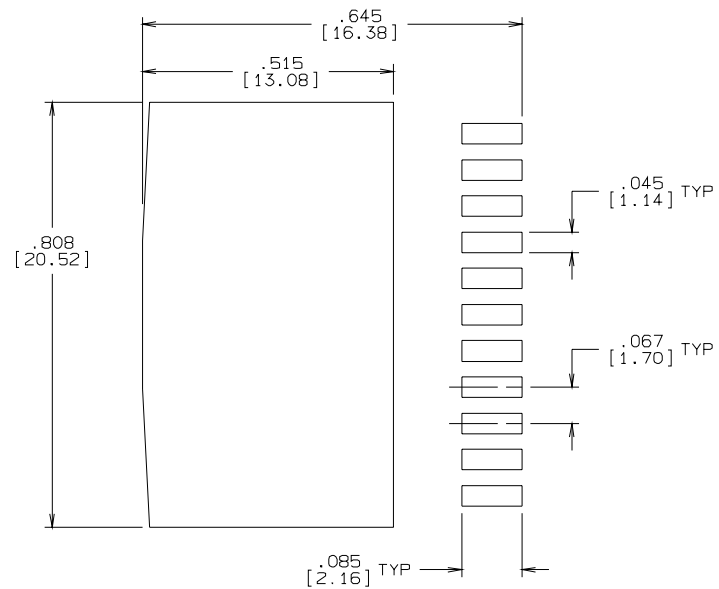
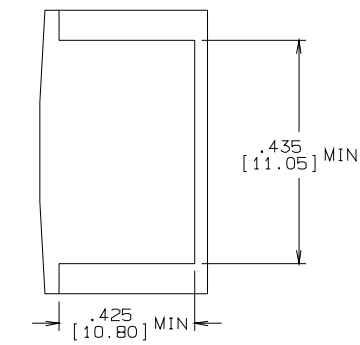


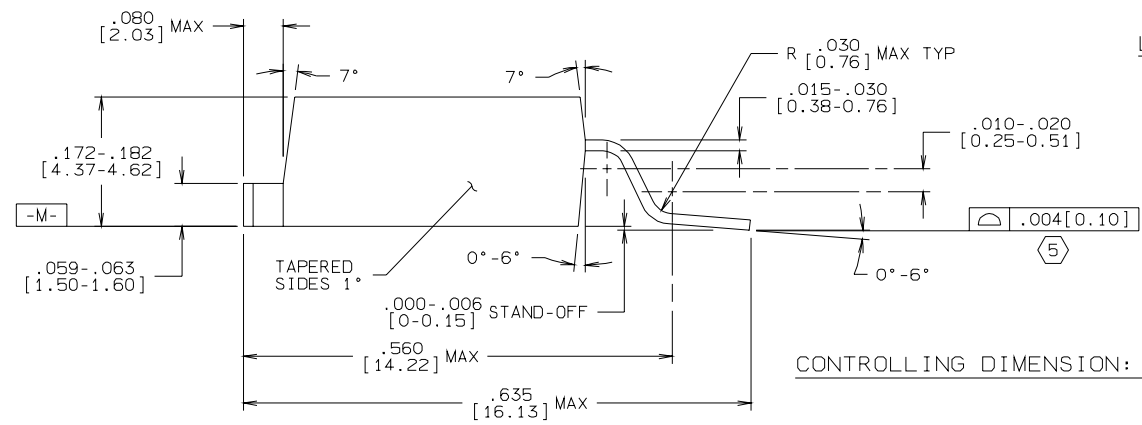
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09899	07/28/93	KES/FL
B	ADD STAND-OFF DIM & NOTE 5.	10151	12/01/93	KES/



LEAD POSITION OVERLAY



BACK VIEW



CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
200 MICRONS / 5.08 MICROMETERS MINIMUM
LEAD/TIN 15/85 ON OLIN 194 COPPER OR EQUIVALENT.
 - MAXIMUM VERTICAL BURR ON HEATSINK
NOT TO EXCEED .003 INCH/ 0.05mm.
 - NO PACKAGE CHIPS, CRACKS OR SURFACE INDENTATION
ALLOWED AFTER FORMING.
 - JEDEC IS IN PROGRESS FOR BALLOT #10-340 AS OF 6/16/93.
- (5) UNDER ALL CONDITIONS LEAD(S) MUST NOT BE ABOVE THE DATUM PLANE -M- AND NO LEADS MAY BE LOWER THAN .006 INCH/0.15mm MEASURED FROM DATUM PLANE -M- TO THE BOTTOM OF THE LEADS.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN <i>Wol Simenon</i>	07/28/93	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.		TO-263, MOLDED, 11 LEAD, SURFACE MOUNT		
ENGR. CHK.				
APPROVAL				
PROJECTION 	SCALE N/A	SIZE C	DRAWING NUMBER MKT-TS11B	REV B
DO NOT SCALE DRAWING		SHEET 1 OF 1		